

SYSTEM, METHOD AND STORAGE MEDIUM FOR PROVIDING THERMAL FEASIBILITY ANALYSIS

Abstract of Disclosure

An embodiment of the invention is a method for performing thermal feasibility analysis for an enclosure containing electronics. The method includes obtaining design parameters related to the enclosure. A thermal feasibility analysis is performed for a plurality of enclosure designs in response to the design parameters. The enclosure designs vary in enclosure material, mounting location of the electronics and presence of a heat sink. The results of the thermal feasibility analysis are displayed for the plurality of enclosure designs.

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Figures

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